

AMENDMENTS TO THE CLAIMS

This listing of the claims will replace all prior versions and listing of the claims in this application. Please amend the claims as follows:

1-14. (canceled).

15. (currently amended) A method comprising:

heating a first element comprising an initial dimension, where the first element is part of an assembly, to a first temperature sufficient to expand the initial dimension to a first dimension, the first dimension greater than the initial dimension; and

removing the first element from the assembly

wherein the first element can only be removed from the assembly when the first element ~~is at~~ reaches the first temperature, and wherein heating the first element from the assembly is a means ~~of de-encrypting to disassemble~~ the assembly.

16. (original) The method of claim 15, wherein a coefficient of thermal expansion of the first element comprises a first value and a coefficient of thermal expansion of the assembly comprises a second value, the first value different than the second value.

17-19. (canceled).

20. (currently amended) The method of claim 15, wherein the first element is a metal having has a thermal expansion coefficient of between approximately 10 micrometers per degree Celsius per meter and approximately 25 micrometers per degree Celsius per meter.

21. (previously presented) The method of claim 15, wherein the first element is fashioned from aluminum.
22. (previously presented) The method of claim 21, wherein the first element further comprises a polymer.
23. (previously presented) The method of claim 22, wherein the polymer has a coefficient of thermal expansion between approximately 0 micrometers per degree Celsius per meter and approximately 1000 micrometers per degree Celsius per meter.
24. (canceled).
25. (previously presented) The method of claim 16, wherein the first element can only be removed from the assembly when the first element is at the first temperature.
26. (canceled).
27. (currently amended) The method of claim 25, wherein heating the first element from the assembly is a means of ~~de-encrypting~~ disassembling the assembly.
28. (previously presented) The method of claim 15, wherein a particular manner, location or sequence of heating is used to remove the first element.

29. (canceled)

30. (canceled)

31. (canceled)

32. (previously presented) The method of claim 15, wherein a means of heating the first element is one or more members selected from the group consisting of a hot liquid, a heating torch, an induction heating oven, a radiator, a heating pad, and a remote heating device.

33. (previously presented) The method of claim 16, wherein a means of heating the first element is one or more members selected from the group consisting of a hot liquid, a heating torch, an induction heating oven, a radiator, a heating pad, and a remote heating device.

34. (previously presented) The method of claim 15 wherein the means of heating the first element is a hot liquid.

35. (canceled).

36. (canceled).

37. (canceled).

38. (previously presented) The method of claim 15, further comprising

a preliminary step of heating the first element and adding the first element which is heated to a second element so as to create the assembly.

39. (currently amended) The method of claim 38, wherein said heating the preliminary step further comprises cooling the first element is from a first temperature to a third temperature wherein the third temperature is lower than the first temperature and the third temperature is sufficient to contract the first dimension to a lesser third dimension to interlock the assembly.

40. (new) A method of disassembling an assembly wherein the assembly is comprised of a first element and a second element comprising:

heating the first element comprising an initial dimension to a first temperature sufficient to expand the initial dimension to a first dimension, the first dimension greater than the initial dimension wherein the first element and the second element are metals; and

removing the first element from the assembly when the first element reaches the first temperature.

41. (new) The method of claim 41, wherein the first element has a thermal expansion coefficient of between approximately 10 micrometers per degree Celsius per meter and approximately 25 micrometers per degree Celsius per meter.

42. (new) A method comprising:

heating a first element comprising an initial diameter, where the first element is part of an assembly, to a first temperature sufficient to expand the initial diameter to a first diameter, the first diameter greater than the initial diameter; and

removing the first element from the assembly
wherein the first element can be removed from the assembly when the first element reaches the first temperature, and wherein heating the first element to the first temperature when associated with the assembly is a means to disassemble the assembly.

43. (new) A method of creating or disassembling an assembly wherein the assembly is comprised of a first element and a second element comprising:
heating the first element comprising an initial dimension to a first temperature sufficient to expand the initial dimension to a first dimension, the first dimension greater than the initial dimension wherein the first dimension allows
removal of the first element from the assembly thereby disassembling the assembly, or
coupling of the first element and the second element thereby creating the assembly.

44. (new) The method of claim 43 wherein the method is for disassembling the assembly.

45. (new) The method of claim 43 wherein the method is for creating the assembly.